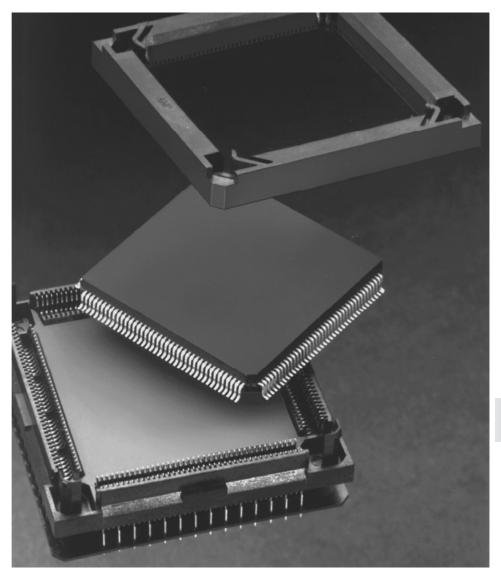
Metric

JEDEC (EIAJ) Metric Quad Flat Pack ICs

Product Facts

- Closed bottom design prevents solder wicking and bridging
- Standoffs facilitate flushing of solder fluxes from under socket
- Horizontal normal force reduces the stress on latches
- Contact wiping removes oxides from package leads
- High pressure tin contacts provide high normal force for interface reliability
- Moulded separation ribs for contact to lead alignment
- Components moulded of high temperature materials
- Mechanical and visual polarisation allows pin #1 alignment
- Cover provides means for handling and testing bumperless packages
- Cover secures device for handling regardless of corner configuration
- Socket design is not sensitive to package stand-off dimension
- Socketing eases prototype evaluation
- Socketing provides repairability in the field
- Socketing enables equipment configuration at the manufacturing level
- Socketing minimises device damage problems due to SMT temperatures
- Socketing allows field updating
- Socketing utilises conventional through-hole soldering processes
- Socket design is compatible with robotic assembly



The AMP Metric PQFP socket provides a method for through-hole socketing of JEDEC (EIAJ) bumperless metric quad flat pack devices. The socket is designed to accept PQFP-style 28mm x 28mm packages on .65mm spacing per proposed JEDEC (EIAJ) Standard

The socket features a twopiece design that allows the device to be first inserted into the plastic cover. Then the cover with the device is secured over the socket housing using the AMP insertion tool. This system protects the delicate gullwing leads and ensures proper lead-to-contact registration.

Available in 144- and 160-position versions, the socket features high temperature housing materials and a sealed bottom allowing it to withstand the rigors of flow soldering lines and automated assembly.

Technical Documents:

Product Specification 108-1348

00-1340

Application Specification

114-1070

Instruction Sheets

408-3289 Hand Tools 408-9772 Pneumatic Tool

MO-108

www.tvcoelectronics.com

Metric

For JEDEC Metric Quad Flat **Pack ICs**

Materials and Finish:

Housing and Cover — High temperature thermoplastic, 94V-0 rated Contacts — Phosphor bronze with 0.00508 [.000200] tin-lead over 0.00127 [.000050] nickel

Performance Characteristics:

Voltage Rating — 250 VAC

Termination Resistance, Dry

Circuit — 20 milliohms max, initial

Dielectric Withstanding Voltage — 750 VAC

Insulation Resistance — 5000megohms

Capacitance — 1 picofarad max.

Durability — 15 cycles

Mating Force — 2.22 N [.5 lb.] max.

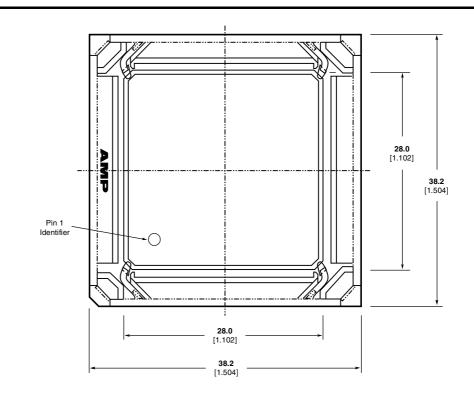
Contact Retention — 3.34 N [12 oz.]

Physical Shock — 50 Gs

Vibration — 15 Gs

Temperature Rating — 255° C to

1105°C

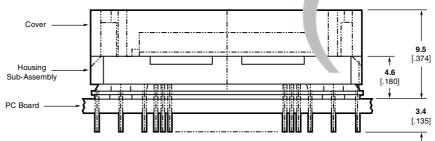




Insertion Hand Tool



Part Number 822253-4



Housing Sub-Assembly

822114-3

822114-4

Extraction Tool



Packaging Quantities:

No. of

Positions

144

160

Cover shipped separately in antistatic tubes, 14 pcs./tube Housing Assembly shipped in antistatic tubes, 14 pcs./tube

5040

Products for Industrial & **Commercial Applications**

Part Number 822254-1

Dimensions are shown for reference purposes only. Conversion Rate: 25.4mm = 1 inch

Dimensions are in inches and millimetres unless otherwise specified. Values in brackets are metric equivalents.

Specifications subject to change.

www.tycoelectronics.com

Cover

822115-3

822115-4

For the very latest product data and news visit anglia.com

Part Numbers